This product complies with the RoHS Directive (EU 2002/95/EC).

MALS068G

Silicon planar type

For ESD protection

■ Overview

MALS068G is optimal for cell phones and AV application, all types of I/O circuits.

■ Features

- High resistance to surge voltages: 30 kV guaranteed
- Low terminal capacitance C_t for low loss, low distortion, and good retention of signal waveforms.

■ Package

- Code
  SSMini2-F4
- Pin Name
  1: Anode
  2: Cathode

■ Marking Symbol: RE

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit
Total power dissipation *1	P_T	150	mW
Electrostatic discharge *2	ESD	±30	kV
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *1: P_T = 150 mW achieved with a printed circuit board.
*2: Test method: IEC61000-4-2 (C = 150 pF, R = 330 Ω, Contact discharge: 10 times)

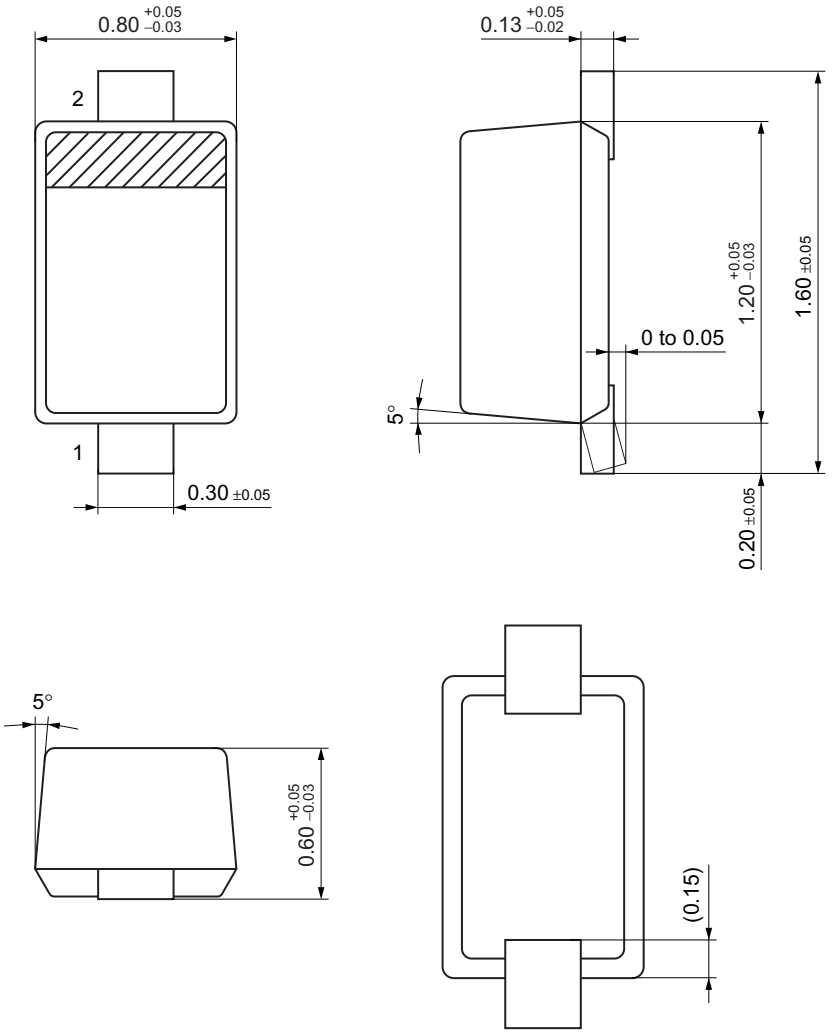
■ Electrical Characteristics T_a = 25°C±3°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Breakdown voltage *	V_{BR}	I_R = 1 mA	6.4	6.8	7.2	V
Reverse current	I_R	V_R = 4 V			0.5	μA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		50		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. *: V_{BR} guaranted 20 ms after current flow.
The temperature must be controlled 25°C for V_{BR} measurement.
V_{BR} value measured at other temperature must be adjusted to V_{BR} (25°C).

SSMini2-F4

Unit: mm



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